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(54) Title: SEMICONDUCTOR DIE OFFSET COMPENSATION VARIATION

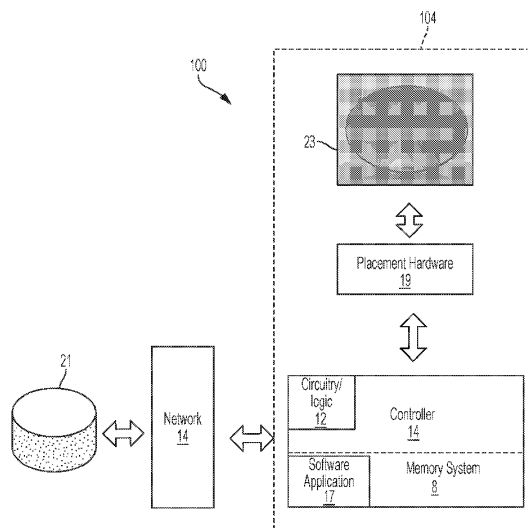


FIG. 1

(57) **Abstract:** A method and system for improving an automated pick and place apparatus semiconductor device placement process is provided. The method includes automatically executing a shift measurement associated with an offset from an original placement of a plurality of semiconductor die of a semiconductor wafer for processing. An associated shift measurement value is retrieved and stored in a database that includes previously retrieved shift measurement values of previously measured shift measurements. Specified models are executed with respect to all shift measurement values and a predicted shift measurement value associated with a future offset for a new plurality of semiconductor die on a new semiconductor wafer for processing is determined. Placement hardware of the pick and place apparatus is placed in multiple positions for generating the new plurality of semiconductor die on the new semiconductor wafer in accordance with the predicted shift measurement value.

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